

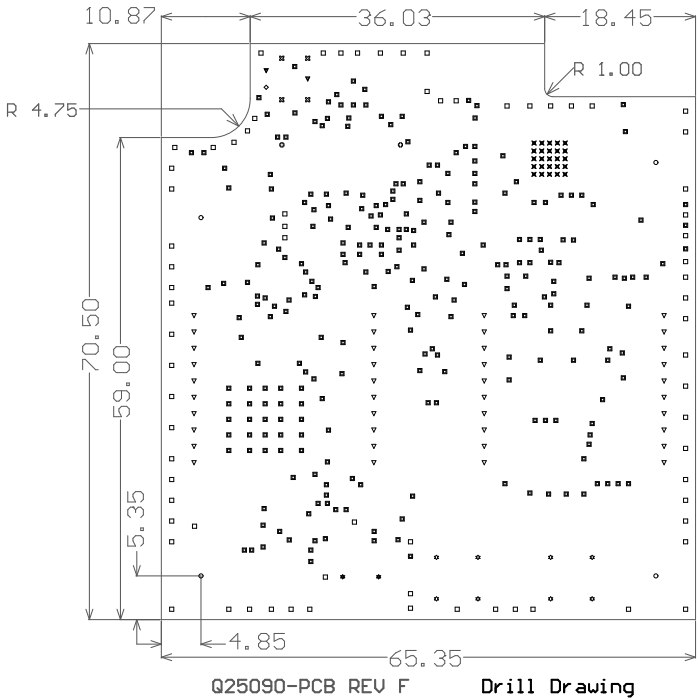
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				[Hatched Pattern]
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer 1		1.40mil		
	Dielectric 1		5.60mil	4.2	
2	Layer 2 (GND)		0.70mil		
	Dielectric 4		20.00mil	4.2	
3	Layer 3 (U)		0.70mil		
	Dielectric 2		5.60mil	4.2	
4	Layer 4 (H)		0.70mil		
	Dielectric 5		20.00mil	4.2	
5	Layer 5 (PWR)		0.70mil		
	Dielectric 3		5.60mil	4.2	
6	Bottom Layer 6		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				

IMPEDANCE REQUIREMENTS:

LAYER	WIDTH	SPACING	REQUIRED IMPEDANCE
1	8.2mil	7mil	90 OHMS DIFFERENTIAL
6	8.2mil	7mil	90 OHMS DIFFERENTIAL

FABRICATION NOTES:

1. MATERIAL SELECTION:
370HR OR EQUIVALENT UL RECOGNIZED ZPMV2 MIN. 130C FLAME CLASS V-0 OR BETTER, MINIMUM CTI RATING OF 175, 0.062 +/- 0.007 THICK. MATERIAL PER IPC-4101
SOLDERABLE SURFACES TO BE ENIG (ELECTROLESS NICKEL IMMERSION GOLD) FINISH.
STARTING COPPER WEIGHT INTERNAL 1/2 oz. MINIMUM
STARTING COPPER WEIGHT EXTERNAL 1/2 oz. MINIMUM
2. SOLDER RESIST: THE USE OF SOLDER RESIST COATING SHALL BE IN ACCORDANCE WITH THE REQUIREMENTS OF IPC-SM-840. ALL SOLDERABLE SURFACES ARE TO BE FREE OF SOLDER RESIST. COLOR - GREEN.
USE LIQUID PHOTOIMAGEABLE RESIST. MATTE FINISH.
3. SILKSCREEN: USE WHITE NON-CONDUCTIVE INK. ALL COMPONENT AND TESTPOINT LANDS ARE TO BE FREE OF INK.
PLACE UL 94V-0 RATING ON SOLDER SIDE IN SILKSCREEN ONLY.
4. MANUFACTURER'S IDENTIFICATION: ADD IN ETCH OR TO SILKSCREEN.
5. ELECTRICAL BARE BOARD TEST REQUIRED.
6. DRILL SIZES ARE FINISHED SIZES AFTER PLATING.
7. FABRICATE TO MEET EU RoHS DIRECTIVE.
8. PCB MUST HAVE UL 94V-0 AND CTI RATING MARKED ON ONE SIDE.
9. MAX WARP AND TWIST NOT TO EXCEED 0.010 PER LINEAR INCH.
10. MIN ANNULAR RING: 0.003. MIN PLATED HOLE WALL THICKNESS 0.001.
11. DIMENSIONAL TOL: XX +/- 0.010. XXX +/- 0.005.
12. FABRICATE IN ACCORDANCE WITH IPC-600 OR IPC-6012 LATEST REVISION. CLASS 2.
13. COPPER THEIVING OF THE SIGNAL LAYERS IS NOT ALLOWED.
14. PCB FABRICATOR IS ALLOWED TO ADJUST PARAMETERS TO ACHIEVE REQUIRED TRACE IMPEDANCE +/-10%.
15. VIPPO TECHNOLOGY REQUIRED - ALL VIAS TO BE TYPE VII NON-CONDUCTIVE EPOXY FILLED AND PLATED OVER.



Symbol	Count	Hole Size	Plated	Hole Tolerance (+)	Hole Tolerance (-)
✕	25	8.00mil	PTH	3.00mil	8.00mil
■	266	12.00mil	PTH	3.00mil	12.00mil
□	73	15.00mil	PTH		
⊗	2	24.00mil	NPTH		
▽	40	32.00mil	PTH		
✱	2	35.00mil	NPTH		
◇	1	39.00mil	NPTH		
▼	2	40.00mil	PTH		
✱	8	59.00mil	PTH	3.00mil	3.00mil
⊗	4	93.00mil	NPTH		
○	4	128.00mil	PTH		
	427 Total				